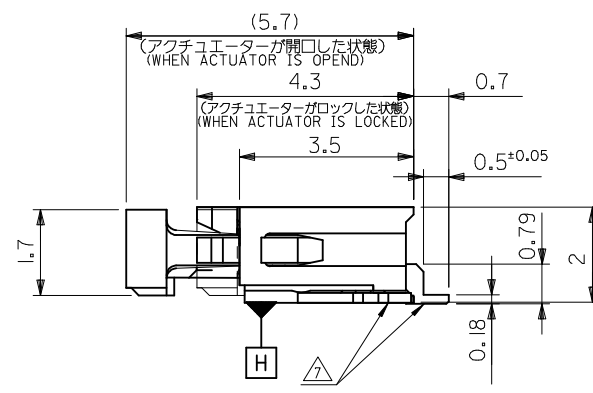
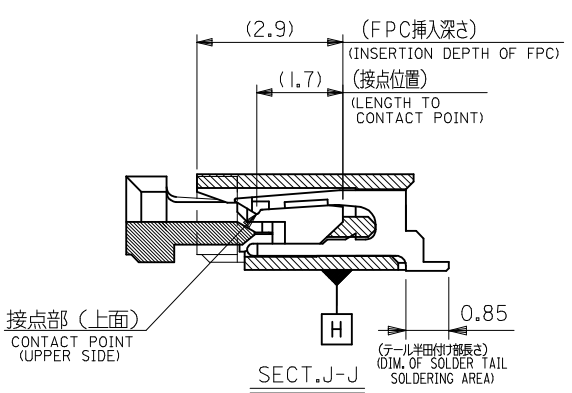


VIEW K
(金具部投影図)
(DETAIL OF FITTING NAIL)

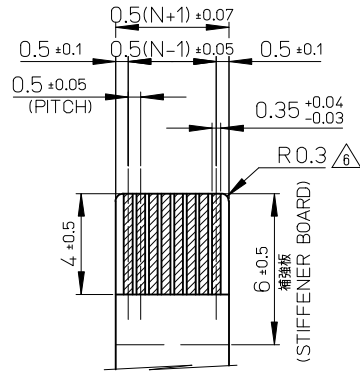


注記 NOTES
1. 使用材料 MATERIAL
ハウジング: ポリアミド (PA), ガラス充填, UL94V-0, ナチュラル(白)
HOUSING: POLYAMIDE, GLASS FILLED, UL94V-0, NATURAL (WHITE)
アクチュエーター: ポリフェニレンスルフィド (PPS), ガラス充填, UL94V-0, 黒
ACTUATOR: POLYPHENYLENE SULFIDE, GLASS FILLED, UL94V-0, BLACK
ターミナル: リン青銅, (t=0.2)
TERMINAL: PHOSPHOR BRONZE
金具: リン青銅, (t=0.2)
FITTING NAIL: PHOSPHOR BRONZE
2. めっき仕様 PLATING
ターミナル TERMINAL
鍍銀ビスマスめっき (1.0 μm以上)
SOLDERABLE BISMUTH PLATING (1.0 MICROMETER MINIMUM)
下地: ニッケルめっき (1.0 μm以上)
UNDER PLATE: NICKEL PLATING (1.0 MICROMETER MINIMUM)
金具: FITTING NAIL
めっき (1.0 μm以上)
下地: ニッケルめっき (1.0 μm以上)
TIN PLATING (1.0 MICROMETER MINIMUM)
UNDER PLATE: NICKEL PLATING (1.0 MICROMETER MINIMUM)
3. エンボスステップ梱包時は、アクチュエータがロックした状態になります。
IN THE PACKAGE, ACTUATOR SHOULD BE LOCKED.
4. 複数極に適用 APPLY FOR EVEN CIRCUIT.
5. パッケージ裏面に貼付する。 FITTING NAIL FOR PREVENTION OF PEELING OF P.W.B. PATTERN.
6. RO:3は、FPCの隣接部にかからないこと RO:3 MUST NOT BE OVERLAPED TO PATTERN OF FPC.
7. シルダータール方向のズレ量、及び金具半田付け面のずれ量は、基準面 H に対し上方向 0.1 MAX., 下方向 0.15 MAX とする。
MISALIGNMENT OF SOLDER TAIL S AND FITTING NAILS FROM [H] UPPER DIRECTION 0.1 MAX., LOWER DIRECTION 0.15 MAX.
8. ELV及びRoHS適合品 ELV AND RoHS COMPLIANT.

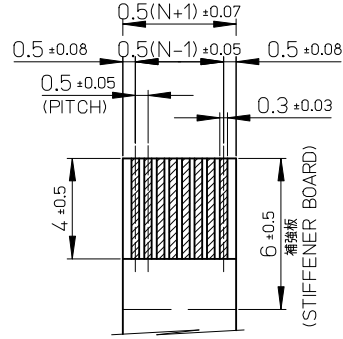
16.1	14.3	10.65	9.5	52745-2033	20
15.6	13.8	10.15	9	52745-1933	19
15.1	13.3	9.65	8.5	52745-1833	18
14.6	12.8	9.15	8	52745-1733	17
14.1	12.3	8.65	7.5	52745-1633	16
13.6	11.8	8.15	7	52745-1533	15
13.1	11.3	7.65	6.5	52745-1433	14
12.6	10.8	7.15	6	52745-1333	13
12.1	10.3	6.65	5.5	52745-1233	12
11.6	9.8	6.15	5	52745-1133	11
11.1	9.3	5.65	4.5	52745-1033	10
10.6	8.8	5.15	4	52745-0933	9
10.1	8.3	4.65	3.5	52745-0833	8
9.6	7.8	4.15	3	52745-0733	7
9.1	7.3	3.65	2.5	52745-0633	6
8.1	6.3	2.65	1.5	52745-0433	4
D	C	B	(A)	EMBOSSED PACKAGE ORDER No. オーダー番号	極数 CKT.

CONNECTOR SERIES NO. : 52745-**22

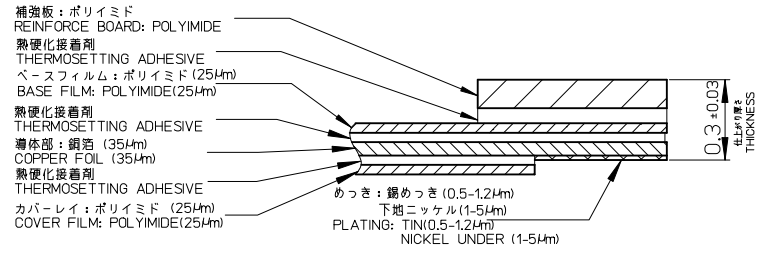
REVISED EC NO: J2013-1168 DRWN: SANUMA 2013/04/15 CHKD: TAKAHASHI 2013/04/15 APPR: KMORIKAWA 2013/04/15	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY	SCALE 10:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY TMORISHITA	DATE 2012/09/06	TITLE 0.5MM FPC CONN ZIF R/A HOUSING ASSY (UPPER CONTACT)	
	10 OVER 30 UNDER	±0.25	CHECKED BY KTAKAHASHI	DATE 2012/09/07		
	30 OVER	±0.3	APPROVED BY KMORIKAWA	DATE 2013/03/15		
ANGULAR	±3 °	MATERIAL NO.	SEE CHART	DOCUMENT NO. SD-52745-055	SHEET NO. 1 OF 2	
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			



適合FPC推奨寸法
 APPLICABLE FPC
 PLATING RECOMMENDED DIMENSION
 仕上がり厚さ: 0.3±0.03
 THICKNESS: 0.3+0.03/-0.03



適合FFC推奨寸法
 APPLICABLE FFC
 PLATING RECOMMENDED DIMENSION
 仕上がり厚さ: 0.3±0.03
 THICKNESS: 0.3+0.03/-0.03

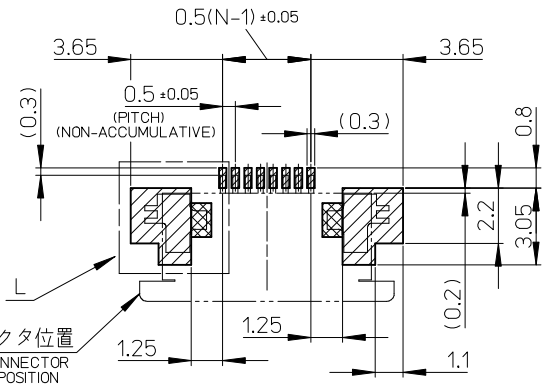
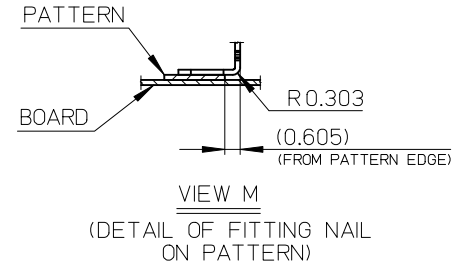
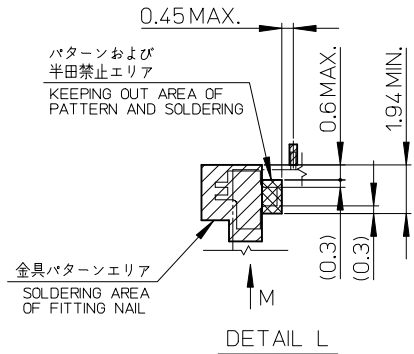


FPC構成推奨仕様
 STRUCTURE OF FPC

FPCについて:
 抜き方向は、導体側から補強板側を推奨致します。
 補強フィルム材質は、ポリイミドを推奨致します。
 接着剤は熱硬化接着剤を推奨致します。
 尚、接着剤の接点部への付着は導通不良の原因になりますので、
 染み出しが無い様お願い致します。

ABOUT FPC:
 RECOMMENDED PUNCHER DIRECTION:
 FROM CONDUCTOR SIDE TO STIFFENER SIDE
 RECOMMENDED MATERIAL: STIFFENER FILM POLYIMIDE
 BONDING AGENT: THERMOSETTING AGENT
 PLEASE PUT APPROPRIATE AMOUNT OF ADHESIVE ON ADHEREND
 BECAUSE THERE IS A POSSIBILITY THAT THE EXTRA ADHESIVE
 CAUSES THE DEFECT IN ELECTRICAL CONTINUITY.

FFC/FPCについて:
 打抜き方向は導体側から補強板側を推奨致します。
 導体部については軟銅箔35μmまたは50μmを推奨致します。
 ABOUT FFC/FPC:
 RECOMMENDED PUNCHER DIRECTION:
 FROM CONDUCTOR SIDE TO STIFFENER FILM SIDE.
 RECOMMENDED CONDUCTOR SPECIFICATION:
 THICKNESS OF SOFT COPPER FOIL: 35MICROMETER
 OR 50 MICROMETER



推奨基板レイアウト
 (マウント面)
 マスク厚: 100 μm
 マスク開口率: 100%
 RECOMMENDED P.C BOARD
 PATTERN DIMENSION
 (MOUNTING SIDE)
 SCREEN THICKNESS: 100 μm
 SCREEN OPEN TATIO: 100%

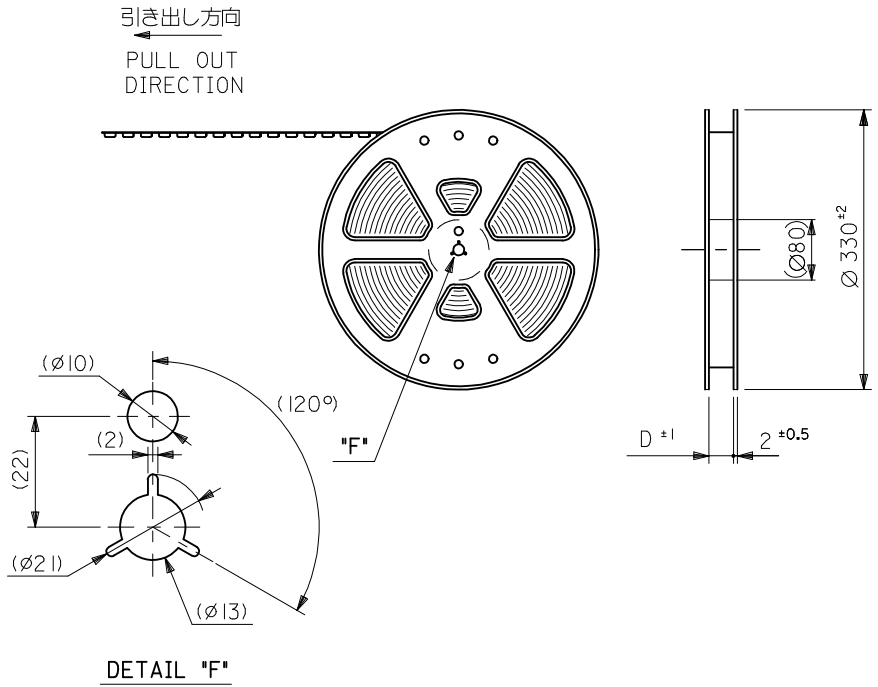
REVISED EC NO: J2013-1168 DRWN:KONDO 2013/03/15 CHKD:KAKAHASHI 2013/03/15 APPR:KMORIKAWA 2013/04/25	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY	SCALE 5:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY TMORISHITA	DATE 2012/09/06	TITLE 0.5MM FPC CONN ZIF R/A HOUSING ASSY (UPPER CONTACT)	
	10 OVER 30 UNDER	±0.25	CHECKED BY KTAKAHASHI	DATE 2013/04/15		
	30 OVER	±0.3	APPROVED BY KMORIKAWA	DATE 2013/03/15		
ANGULAR	±3 °	MATERIAL NO. ENTER PART		DOCUMENT NO. SD-52745-055	SHEET NO. 2 OF 2	
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			

注記 NOTES

- 製品番号 52745-***22の梱包状態はアクチュエータがロックした状態とする。
詳細寸法については図面SD-52745-055を参照下さい。
IN THE PACKAGE,ACTUATOR OF PART NO.52745-***22 SHOULD BE LOCKED
RE DETAILED DIMENSIONS,SEE SD-52745-055
- 梱包数量：1000個/リール
NUMBER OF CONNECTORS:1000PCS/REEL
- リードテープ長さ LEAD TAPE LENGTH

トップテープ リーダー部 175 ±25	トップテープ 未接着部 25 ±5
TOP TAPE LEADER PART	TOP TAPE NON-BONDED PART

リール部 (空部) LEADER PART (EMPTY) 120 ±20	部品挿入部 COMPONENT SUPPLIER	末端部 (空部) TAIL PART (EMPTY) 150 ±40
--	--------------------------------	--
- カバーテープの剥離強度については、IEC60286-3に準拠
COVER TAPE PEEL FORCE IS DEFINED BY IEC 60286-3.

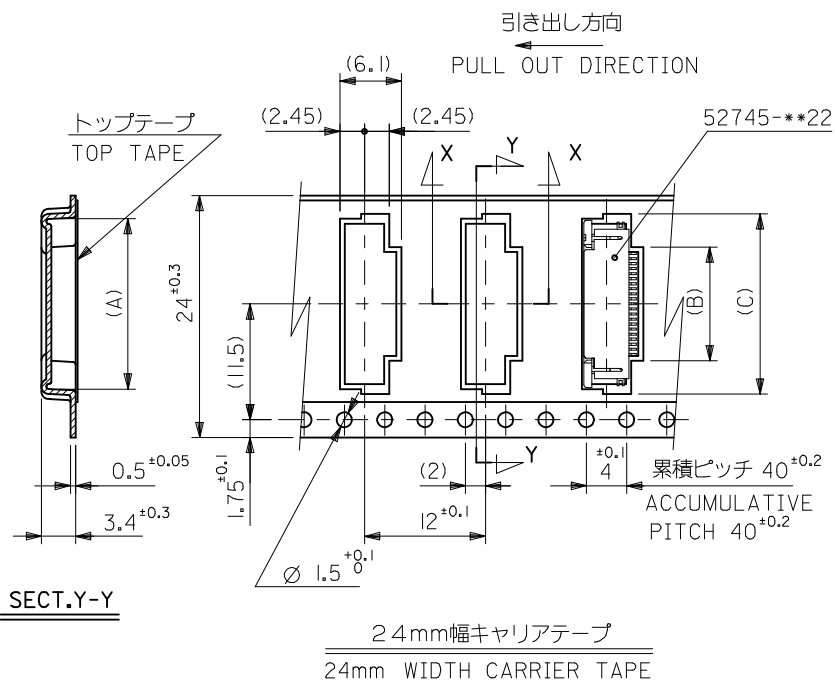


5. 材料
 キャリアテープ：ポリプロピレン (PP)
 トップテープ：PET, PE, PEF
 リール：ポリスチレン (PS) <リサイクル材を含む>

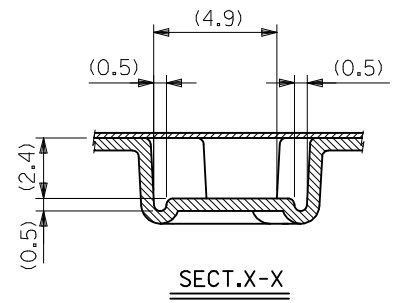
MATERIAL CARRIER TAPE:POLYPROPYLENE
 TOP TAPE:PET,PE,PEF
 REEL:POLYSTYREN(PS)
 <RECYCLE MATERIAL CONTAINED>

6. ELV及RoHS適合品
 ELV AND RoHS COMPLIANT

RELEASED EC NO.: J2013-1014 DRWN:TMORISHITA 2012/09/05 CHKD:KTAKAHASHI 2012/09/07 APPR:KMORIKAWA 2013/03/15	DESCRIPTION REV: 0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		10 UNDER	±0.2	DRAWN BY TMORISHITA	DATE 2012/09/05	TITLE EMBOSS TAPE PACKAGED FOR 0.5MM FPC CONN ZIF R/A HOUSING ASSY molex DOCUMENT NO. SD-52745-056 SHEET NO. 1 OF 3				
		10 OVER 30 UNDER	±0.25	CHECKED BY KTAKAHASHI	DATE 2012/09/07					
		30 OVER	±0.3	APPROVED BY KMORIKAWA	DATE 2013/03/15					
ANGULAR ±3 °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO. SEE CHART						
SIZE A3 THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION										



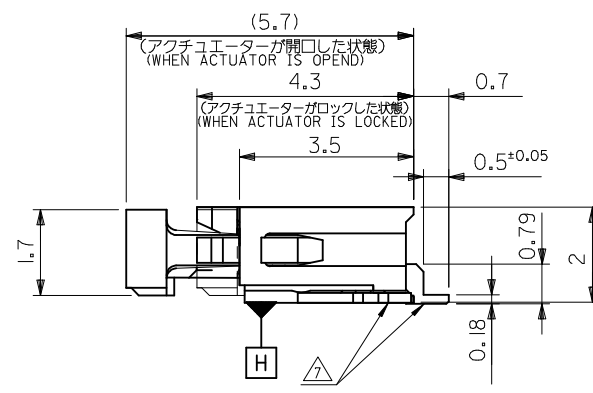
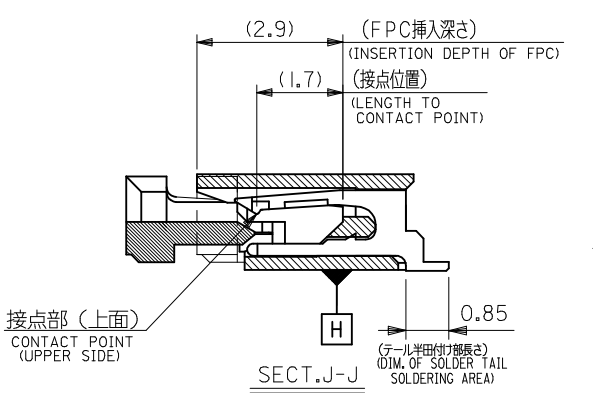
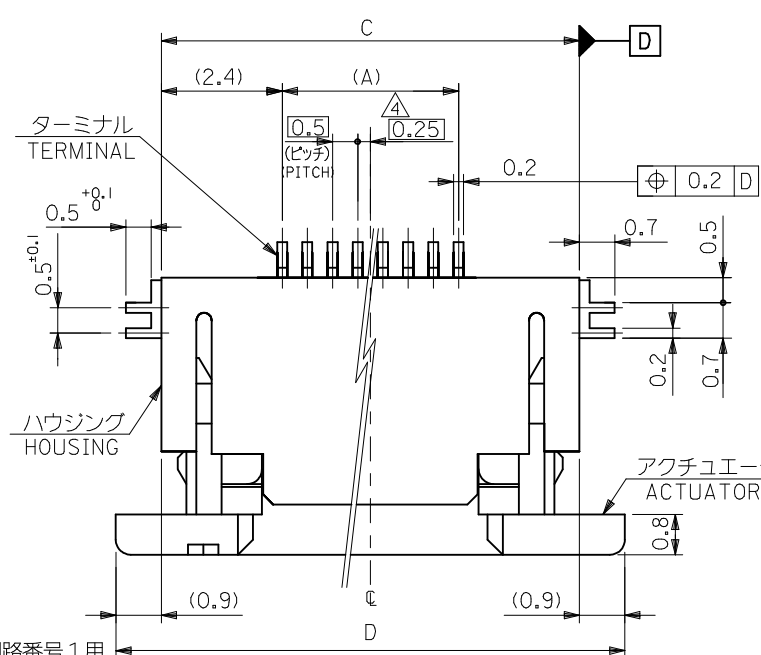
SECT.Y-Y



24	25.5	17.4	10.8	16.4	52745-2033	20
		16.9	10.3	15.9	-1933	19
		16.4	9.8	15.4	-1833	18
		15.9	9.3	14.9	-1733	17
		15.4	8.8	14.4	-1633	16
		14.9	8.3	13.9	-1533	15
		14.4	7.8	13.4	-1433	14
		13.9	7.3	12.9	-1333	13
		13.4	6.8	12.4	-1233	12
		12.9	6.3	11.9	-1133	11
		12.4	5.8	11.4	-1033	10
		11.9	5.3	10.9	-0933	9
		11.4	4.8	10.4	-0833	8
		10.9	4.3	9.9	-0733	7
10.4	3.8	9.4	52745-0633	6		
キャリアテープ幅 CARRIER TAPE WIDTH		D	(C)	(B)	(A)	EMBOSSED PACKAGE ORDER No. オ-ダ-番号
CONNECTOR SERIES NO. : 52745-**-22						

RELEASED EC NO. J2013-1014 DRWN:TMORISHITA 2012/09/05 CHKD:KTAKAHASHI 2012/09/07 APPR:KMORIKAWA 2013/03/15	GENERAL TOLERANCES (UNLESS SPECIFIED)	
	10 UNDER	±0.2
	10 OVER 30 UNDER	±0.25
	30 OVER	±0.3
	ANGULAR	±3 °
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		

DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
DRAWN BY TMORISHITA	DATE 2012/09/05	TITLE EMBOSS TAPE PACKAGED FOR 0.5MM FPC CONN ZIF R/A HOUSING ASSY		
CHECKED BY KTAKAHASHI	DATE 2012/09/07	molex		
APPROVED BY KMORIKAWA	DATE 2013/03/15			
MATERIAL NO.	DOCUMENT NO. SD-52745-056	SHEET NO. 2 OF 3		
SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			



注記NOTES

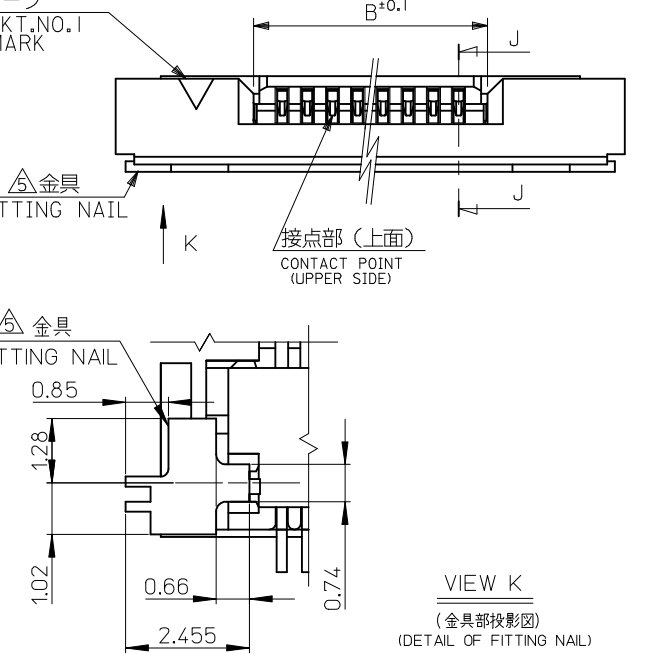
1.使用材料
MATERIAL
ハウジング:ポリアミド(R/PA),ガラス充填,UL94V-0,ナチュラル(白)
HOUSING:POLYAMIDE, GLASS FILLED, UL94V-0, NATURAL (WHITE)
アクチュエータ:ポリフェニレンスルフィド(PPS),ガラス充填,UL94V-0,黒
ACTUATOR:POLYPHENYLENE SULFIDE, GLASS FILLED, UL94V-0, BLACK
ターミナル:リン青銅, (t=0.2)
TERMINAL:PHOSPHOR BRONZE
金具:リン青銅, (t=0.2)
FITTING NAIL:PHOSPHOR BRONZE

2.めっき仕様
PLATING
ターミナル
鍍銀ピンスマめっき(1.0μm以上)
下地:ニッケルめっき(1.0μm以上)
TIN SILVER BISMUTH PLATING (1.0 MICROMETER MINIMUM)
UNDER PLATE:NICKEL PLATING (1.0 MICROMETER MINIMUM)
金具:FITTING NAIL
めっき(1.0μm以上)
下地:ニッケルめっき(1.0μm以上)
TIN PLATING (1.0 MICROMETER MINIMUM)
UNDER PLATE:NICKEL PLATING (1.0 MICROMETER MINIMUM)

3.エンボスステップ梱包時は、アクチュエータがロックした状態になります。
IN THE PACKAGE, ACTUATOR SHOULD BE LOCKED.

4. 複数極に適用
APPLY FOR EVEN CIRCUIT.
5. パッケージ裏面に貼る
FITTING NAIL FOR PREVENTION OF PEELING OF P.W.B. PATTERN.
6. R0.3は、FPCの隣接部にかからないこと
R0.3 MUST NOT BE OVERLAPED TO PATTERN OF FPC.
7. シルダータール方向のズレ量、及び金具半田付け面のずれ量は、基準面 H に対し上方向0.1 MAX., 下方向0.15MAXとする。
MISALIGNMENT OF SOLDER TAIL S AND FITTING NAILS FROM [H] UPPER DIRECTION 0.1 MAX., LOWER DIRECTION 0.15 MAX.

8. ELV及びRoHS適合品
ELV AND RoHS COMPLIANT.



16.1	14.3	10.65	9.5	52745-2033	20
15.6	13.8	10.15	9	52745-1933	19
15.1	13.3	9.65	8.5	52745-1833	18
14.6	12.8	9.15	8	52745-1733	17
14.1	12.3	8.65	7.5	52745-1633	16
13.6	11.8	8.15	7	52745-1533	15
13.1	11.3	7.65	6.5	52745-1433	14
12.6	10.8	7.15	6	52745-1333	13
12.1	10.3	6.65	5.5	52745-1233	12
11.6	9.8	6.15	5	52745-1133	11
11.1	9.3	5.65	4.5	52745-1033	10
10.6	8.8	5.15	4	52745-0933	9
10.1	8.3	4.65	3.5	52745-0833	8
9.6	7.8	4.15	3	52745-0733	7
9.1	7.3	3.65	2.5	52745-0633	6
8.1	6.3	2.65	1.5	52745-0433	4
D	C	B	(A)	EMBOSSED PACKAGE ORDER No. オート番号	極数 CKT.

CONNECTOR SERIES NO. : 52745-**22

REVISED EC NO: J2013-1168 DRWN:NASUNUMA 2013/04/15 CHKD:KAKAHASHI 2013/04/15 APPR:KMORIKAWA 2013/04/15	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY	SCALE 10:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY TMORISHITA	DATE 2012/09/06	TITLE 0.5MM FPC CONN ZIF R/A HOUSING ASSY (UPPER CONTACT)	
	10 OVER 30 UNDER	±0.25	CHECKED BY KAKAHASHI	DATE 2012/09/07	molex	
	30 OVER	±0.3	APPROVED BY KMORIKAWA	DATE 2013/03/15	DOCUMENT NO. SD-52745-055	SHEET NO. 1 OF 2
A	ANGULAR ±3 ° DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3	SEE CHART THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		